# -5 V Differential ECL to TTL **Translator**

The MC10ELT/100ELT25 is a differential ECL to TTL translator. Because ECL levels are used, a +5 V, -5.2 V (or -4.5 V) and ground are required. The small outline 8-lead package and the single gate of the ELT25 makes it ideal for those applications where space, performance and low power are at a premium.

The V<sub>BB</sub> pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V<sub>BB</sub> as a switching reference voltage. V<sub>BB</sub> may also rebias AC coupled inputs. When used, decouple V<sub>BB</sub> and V<sub>CC</sub> via a 0.01 µF capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V<sub>BB</sub> should be left open.

The 100 Series contains temperature compensation.

- 2.6 ns Typical Propagation Delay
- 100 MHz F<sub>MAX</sub> CLK
- 24 mA TTL Outputs
- Flow Through Pinouts
- Operating Range:  $V_{CC} = 4.5 \text{ V}$  to 5.5 V with GND = 0 V;  $V_{EE} = -4.2 \text{ V to } -5.7 \text{ V with GND} = 0 \text{ V}$
- Internal Input 50 KΩ Pulldown Resistors
- Q Output will default HIGH with inputs open or < 1.3 V

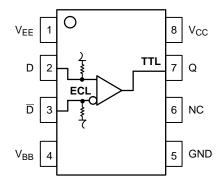


Figure 1. 8-Lead Pinout and Logic Diagram (Top View)



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#### **MARKING DIAGRAMS\***



SOIC-8 **D SUFFIX CASE 751** 







TSSOP-8 **DT SUFFIX CASE 948R** 





H = MC10K = MC100 L = Wafer Lot Y = YearW = Work Week

A = Assembly Location

\*For additional marking information, refer to Application Note AND8002/D.

#### **PIN DESCRIPTION**

PIN	FUNCTION
D, D Q V <sub>BB</sub> V <sub>CC</sub> V <sub>EE</sub> GND NC	ECL Differential Inputs TTL Output Reference Voltage Output Positive Supply Negative Supply Ground No Connect

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MC10ELT25D	SOIC-8	98 Units/Rail
MC10ELT25DR2	SOIC-8	2500 Tape & Reel
MC100ELT25D	SOIC-8	98 Units/Rail
MC100ELT25DR2	SOIC-8	2500 Tape & Reel
MC10ELT25DT	TSSOP-8	98 Units/Rail
MC10ELT25DTR2	TSSOP-8	2500 Tape & Reel
MC100ELT25DT	TSSOP-8	98 Units/Rail
MC100ELT25DTR2	TSSOP-8	2500 Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### **ATTRIBUTES**

	Value				
Internal Input Pulldown Resistors	75 kΩ				
Internal Input Pullup Resistors	N/A				
ESD Protection Human Body Model Machine Model		> 1 KV > 400 V			
Moisture Sensitivity (Note 1)		Level 1			
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in			
Transistor Count		38 Devices			
Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test					

<sup>1.</sup> Refer to Application Note AND8003/D for additional information.

### **MAXIMUM RATINGS**

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V <sub>CC</sub>	Positive Power Supply	GND = 0 V	V <sub>EE</sub> = -5.0 V	7	V
V <sub>EE</sub>	Negative Power Supply	GND = 0 V	V <sub>CC</sub> = +5.0 V	-8	V
V <sub>IN</sub>	Input Voltage	GND = 0 V		0 to V <sub>EE</sub>	V
I <sub>BB</sub>	V <sub>BB</sub> Sink/Source			± 0.5	mA
T <sub>A</sub>	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-8 SOIC-8	190 130	°C/W
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8	41 to 44	°C/W
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W
$\theta_{JC}$	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44 ± 5%	°C/W
T <sub>sol</sub>	Wave Solder	< 2 to 3 sec @ 248°C		265	°C

Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If stress limits are exceeded device functional operation is not implied, damage may occur and reliability may be affected. Functional operation should be restricted to the Recommended Operating Conditions.

### 10ELT SERIES NECL INPUT DC CHARACTERISTICS V<sub>CC</sub> = 5.0 V; V<sub>EE</sub> = -5.0 V; GND = 0 V (Note 2)

		-40°C 25°C			85°C						
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
V <sub>IH</sub>	Input HIGH Voltage (Single-Ended) (Note 3)	-1230		-890	-1130		-810	-1060		-720	mV
V <sub>IL</sub>	Input LOW Voltage (Single-Ended) (Note 3)	-1950		-1500	-1950		-1480	-1950		-1445	mV
V <sub>BB</sub>	Output Voltage Reference	-1.43		-1.30	-1.35		-1.25	-1.31		-1.19	V
V <sub>IHCMR</sub>	Input HIGH Voltage Common Mode Range (Differential) (Notes 3 and 4)	-2.8		0.0	-2.8		0.0	-2.8		0.0	٧
I <sub>IH</sub>	Input HIGH Current			255			175			175	μΑ
I <sub>IL</sub>	Input LOW Current	0.5			0.5			0.3			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 2. Input parameters vary 1:1 with GND.  $V_{\mbox{\footnotesize EE}}$  can vary +0.06 V / –0.5 V.
- 3. TTL output  $R_L = 500 \Omega$  to GND
- 4.  $V_{IHCMR}$  min varies 1:1 with  $V_{EE}$ ,  $V_{IHCMR}$  max varies 1:1 with GND.

# 100ELT SERIES NECL INPUT DC CHARACTERISTICS $V_{CC} = 5.0 \text{ V}$ ; $V_{EE} = -5.0 \text{ V}$ ; GND = 0 V (Note 5)

		-40°C		25°C		85°C					
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
V <sub>IH</sub>	Input HIGH Voltage (Single–Ended) (Note 6)	-1165		-880	-1165		-880	-1165		-880	mV
V <sub>IL</sub>	Input LOW Voltage (Single-Ended) (Note 6)	-1810		-1475	-1810		-1475	-1810		-1475	mV
$V_{BB}$	Output Voltage Reference	-1.38		-1.26	-1.38		-1.26	-1.38		-1.26	V
V <sub>IHCMR</sub>	Input HIGH Voltage Common Mode Range (Differential) (Notes 6 and 7)	-2.8		0.0	-2.8		0.0	-2.8		0.0	٧
I <sub>IH</sub>	Input HIGH Current			255			175			175	μΑ
I <sub>IL</sub>	Input LOW Current	0.5			0.5			0.5			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 5. Input parameters vary 1:1 with GND.  $V_{EE}$  can vary +0.8 V / -0.5 V.
- 6. TTL output  $R_L = 500 \Omega$  to GND
- 7.  $V_{IHCMR}$  min varies 1:1 with  $V_{EE}$ ,  $V_{IHCMR}$  max varies 1:1 with GND.

# TTL OUTPUT DC CHARACTERISTICS $V_{CC}$ = 4.5 V to 5.5 V; $T_A$ = -40°C to +85°C

Symbol	Characteristic	Condition	Min	Тур	Max	Unit
V <sub>OH</sub>	Output HIGH Voltage	$I_{OH} = -3.0 \text{ mA}$	2.4			V
V <sub>OL</sub>	Output LOW Voltage	I <sub>OL</sub> = 24 mA			0.5	V
I <sub>CCH</sub>	Power Supply Current			11	16	mA
I <sub>CCL</sub>	Power Supply Current			13	18	mA
I <sub>EE</sub>	Negative Power Supply Current			15	21	mA
I <sub>OS</sub>	Output Short Circuit Current		-150		-60	mA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

AC CHARACTERISTICS V<sub>CC</sub>= 5.0 V; V<sub>EE</sub>= -5.0 V; GND= 0 V (Note 8 and Note 9)

			-40°C 25		25°C			85°C			
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f <sub>max</sub>	Maximum Toggle Frequency					100					MHz
t <sub>PLH</sub>	Propagation Delay @ 1.5 V	1.7		3.6	1.7		3.6	1.7		3.6	ns
t <sub>PHL</sub>	Propagation Delay @ 1.5 V	2.6		4.1	2.6		4.1	2.6		4.1	ns
t <sub>JITTER</sub>	Random Clock Jitter (RMS)					35					ps
t <sub>r</sub> t <sub>f</sub>	Output Rise/Fall Times QTTL 10% – 90%					1.9 2.3					ns
$V_{PP}$	Input Swing (Note 10)	200		1000	200		1000	200		1000	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 8.  $V_{CC}$  can vary  $\pm$  0.25 V.
- $V_{EE}$  can vary +0.06 V / -0.5 V for 10ELT;  $V_{EE}$  can vary +0.8 V / -0.5 V for 100ELT. 9.  $R_L$  = 500  $\Omega$  to GND and  $C_L$  = 20 pF to GND. Refer to Figure 2.
- 10. V<sub>PP</sub>(min) is the minimum input swing for which AC parameters are guaranteed. The device has a DC gain of ≈ 40.

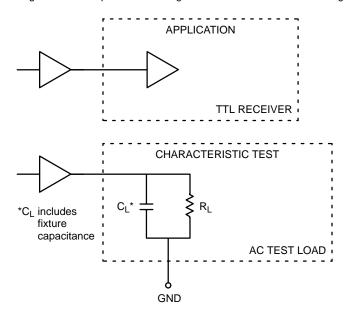


Figure 2. TTL Output Loading Used for Device Evaluation

### **Resource Reference of Application Notes**

AN1404 - ECLinPS Circuit Performance at Non–Standard V<sub>IH</sub> Levels

AN1405 - ECL Clock Distribution Techniques

AN1406 - Designing with PECL (ECL at +5.0 V)

AN1503 - ECLinPS I/O SPICE Modeling Kit

AN1504 – Metastability and the ECLinPS Family

AN1560 – Low Voltage ECLinPS SPICE Modeling Kit

AN1568 - Interfacing Between LVDS and ECL

AN1596 - ECLinPS Lite Translator ELT Family SPICE I/O Model Kit

AN1650 - Using Wire-OR Ties in ECLinPS Designs

AND8001 - The ECL Translator Guide

AND8001 - Odd Number Counters Design

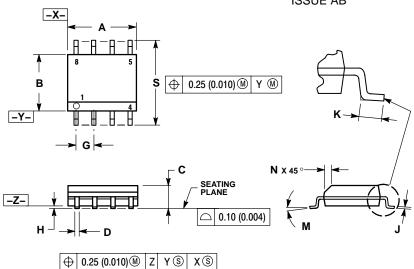
AND8002 - Marking and Date Codes

AND8020 – Termination of ECL Logic Devices

AND8090 – AC Characteristics of ECL Devices

#### **PACKAGE DIMENSIONS**

#### SOIC-8 **D SUFFIX** PLASTIC SOIC PACKAGE CASE 751-07 **ISSUE AB**



#### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.

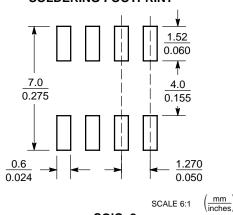
- 2. CONTROLLING DIMENSION. MILLIMETER.
  3. DIMENSION A AND B DO NOT INCLUDE
  MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006)
  PER SIDE.
- PER SIDE.

  5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

  6. 751–01 THRU 751–06 ARE OBSOLETE. NEW STANDARD IS 751–07.

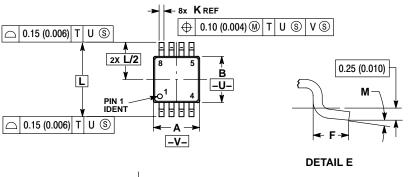
	MILLIN	METERS	INC	HES		
DIM	MIN	MAX	MIN	MAX		
Α	4.80	5.00	0.189	0.197		
В	3.80	4.00	0.150	0.157		
C	1.35	1.75	0.053	0.069		
D	0.33	0.51	0.013	0.020		
G	1.27	7 BSC	0.050 BSC			
Η	0.10	0.25	0.004	0.010		
7	0.19	0.25	0.007	0.010		
K	0.40	1.27	0.016	0.050		
М	0 °	8 °	0 °	8 °		
Ν	0.25	0.50	0.010	0.020		
S	5.80	6.20	0.228 0.244			

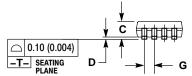
#### **SOLDERING FOOTPRINT**

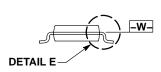


### **PACKAGE DIMENSIONS**

#### TSSOP-8 **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A**







- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
- 2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION A DOES NOT INCLUDE MOLD FLASH.
  PROTRUSIONS OR GATE BURRS. MOLD FLASH
  OR GATE BURRS SHALL NOT EXCEED 0.15
  (0.006) PER SIDE.
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD
  FLASH OR PROTRUSION. INTERLEAD FLASH OR
  PROTRUSION SHALL NOT EXCEED 0.25 (0.010)
  DED SIDE.
- PER SIDE. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.

  6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	METERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	2.90	3.10	0.114	0.122	
В	2.90	3.10	0.114	0.122	
С	0.80	1.10	0.031	0.043	
D	0.05	0.15	0.002	0.006	
F	0.40	0.70	0.016	0.028	
G	0.65	BSC	0.026	BSC	
K	0.25	0.40	0.010	0.016	
L	4.90	BSC	0.193 BSC		
М	0.0	6 °	0 °	6°	

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